



SOT684-30(D)

HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimple wettable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

5 August 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN56
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-05-2021
Manufacturer package code	98ASA01771D

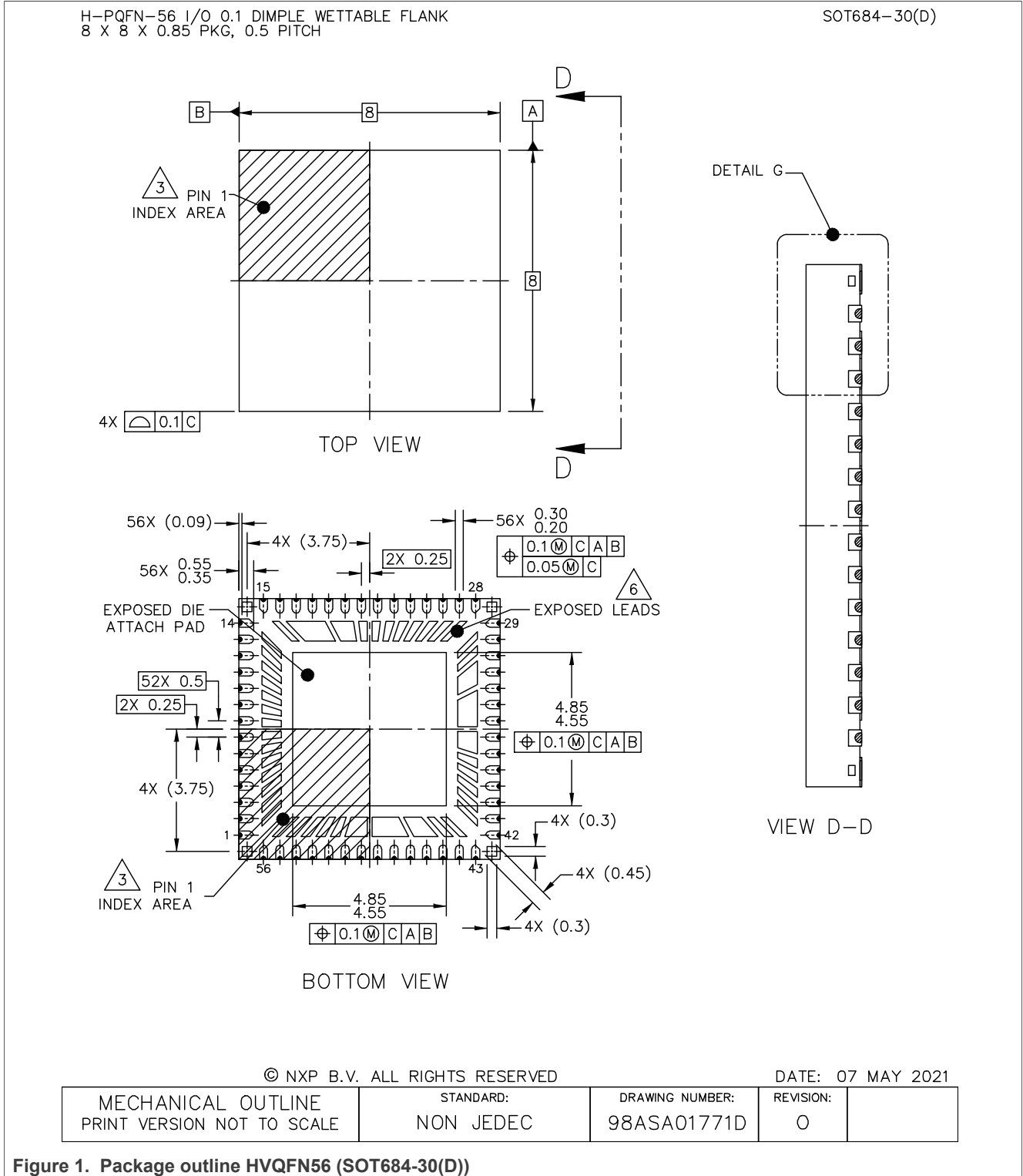
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	7.9	8	8.1	mm
package width	7.9	8	8.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	56	-	



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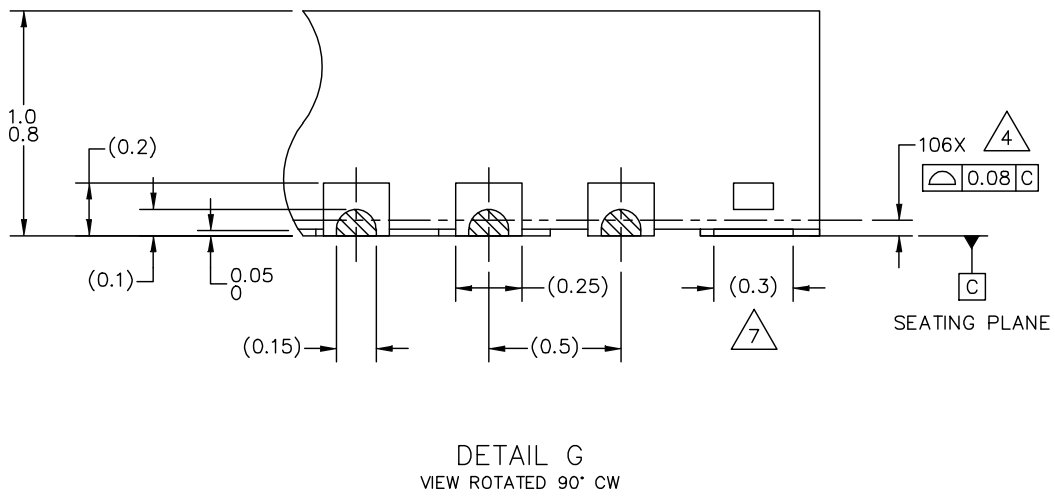
2 Package outline



HVQFN56, thermal enhanced very thin quad flat package, no leads, 56 terminals, 0.1 mm dimple
wetable flank, 0.5 mm pitch, 8 mm x 8 mm x 0.85 mm body

H-PQFN-56 I/O 0.1 DIMPLE WETTABLE FLANK
8 X 8 X 0.85 PKG, 0.5 PITCH

SOT684-30(D)



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Figure 2. Package outline detail of HVQFN56 (SOT684-30(D))

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3 Soldering

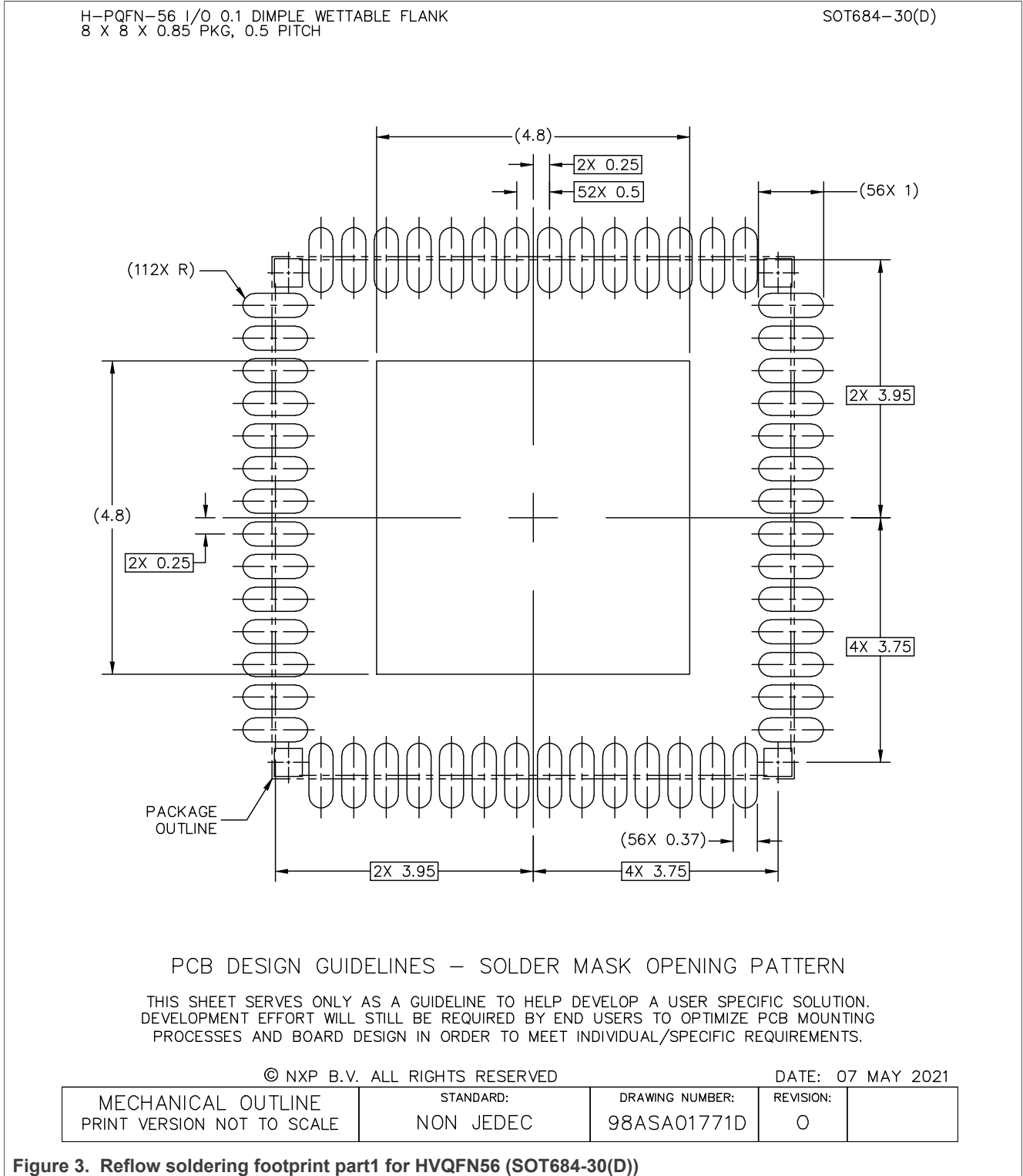
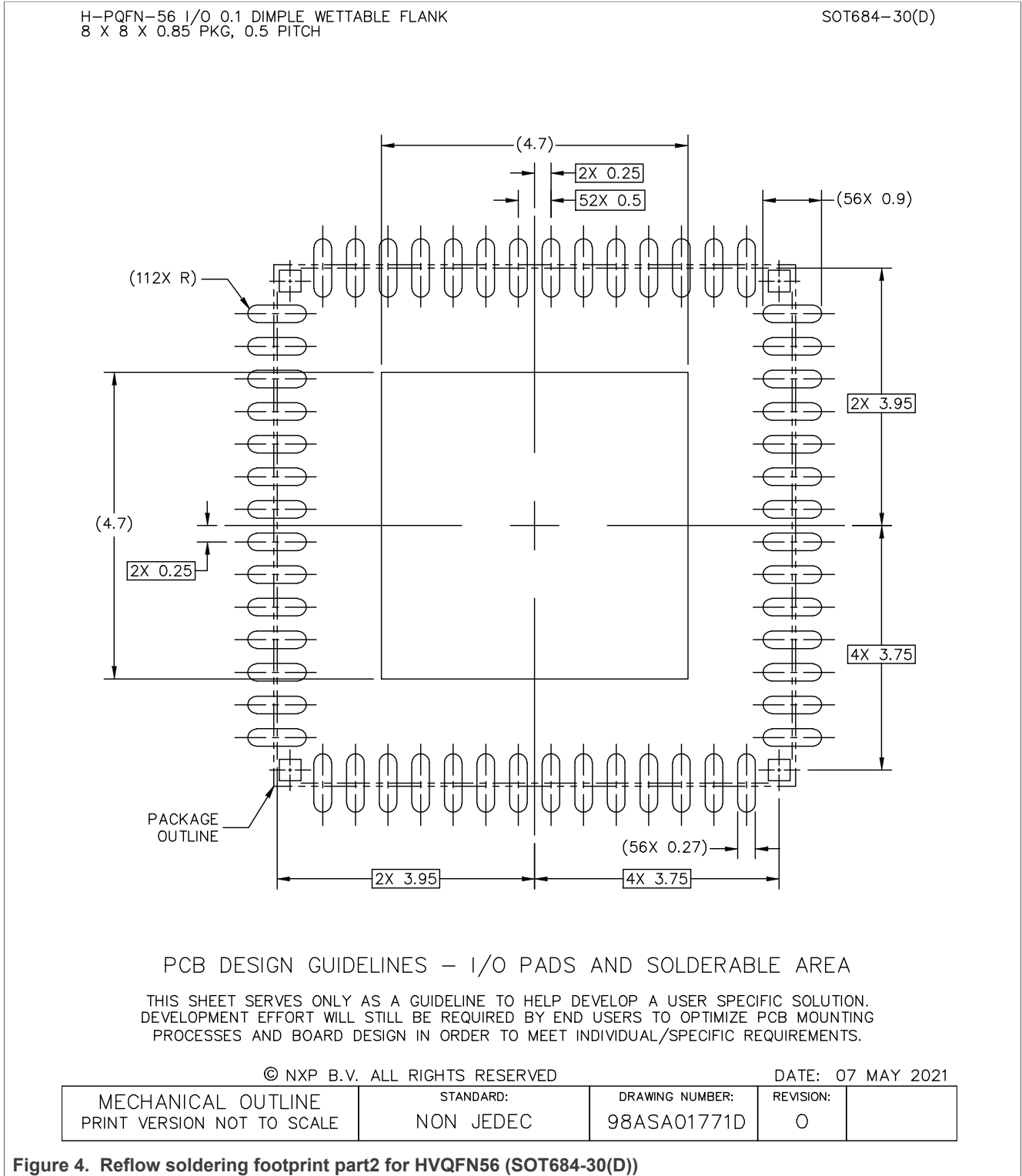
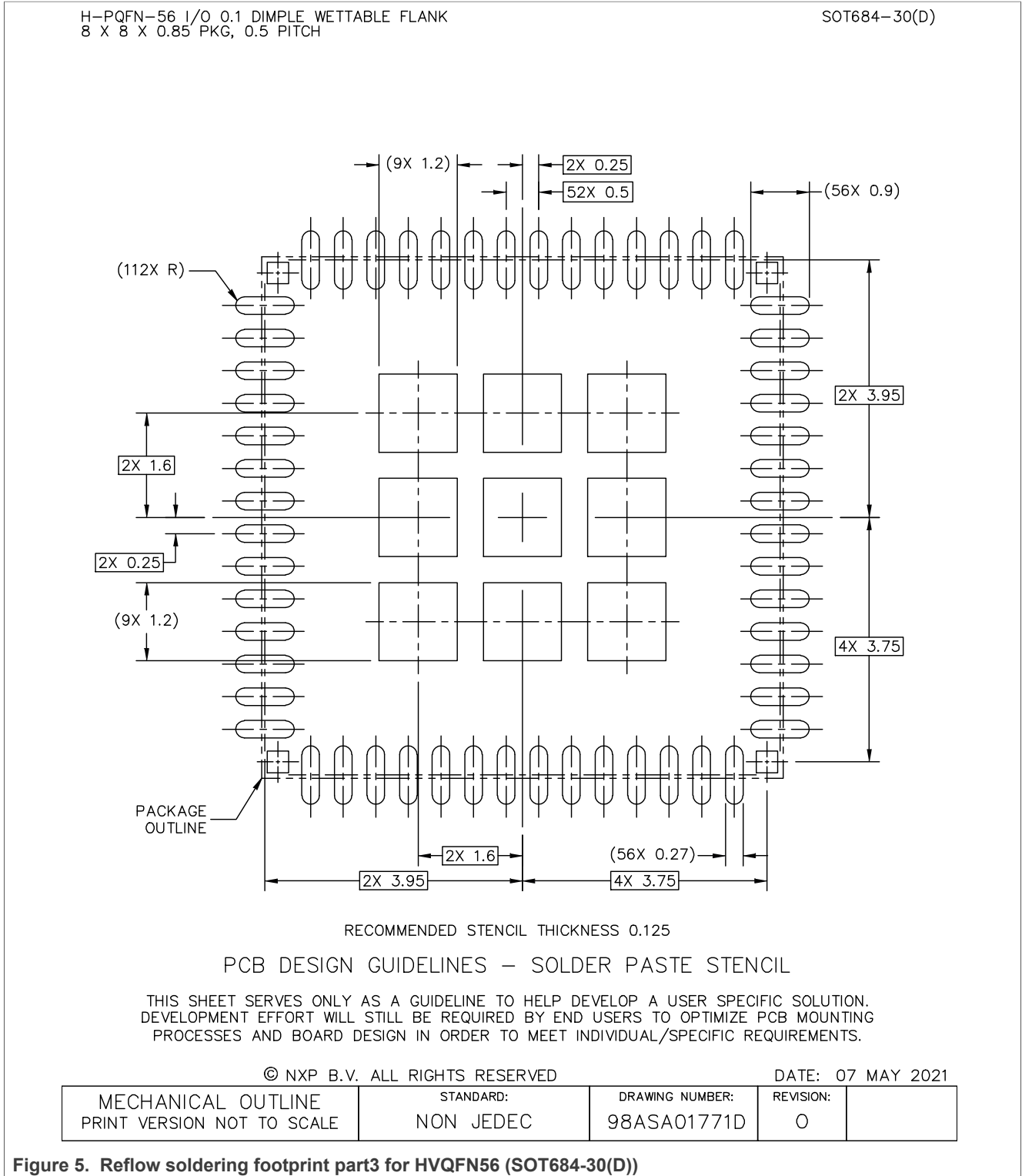


Figure 3. Reflow soldering footprint part1 for HVQFN56 (SOT684-30(D))

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8 X 8 X 0.85 PKG, 0.5 PITCH

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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.
6. EXPOSED INNER LEADS ARE NOT TO BE SOLDERED TO THE PCB. THIS AREA MUST BE COVERED BY SOLDERMASK IN ORDER TO ROUTE IN THIS AREA.
7. ANCHORING PADS.

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Figure 6. Package outline note HVQFN56 (SOT684-30(D))

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Contents

1	Package summary	1
2	Package outline	2
3	Soldering	4
4	Legal information	8